•	2	3		4	5		6	- 1	7		0
	-	-	I	-	T		-	l			
DIVI	Cianal han h	16 61 mal	0 600006	ton m	Soldering instruc	tions	-		-		
ARTING UNIVERSITY	Signal har-bu	15 04 IIIal	e connect	/R 3 10†	Bus						
			_					ed in a dip, flow or		hs. Otherwise, t	hey might become
					contaminated as	a result of solderi	ng operations or de	eformed as a result	of overheating.		
General information	:			:	(1) For prototype	s and short runs p	protect the connecto	ors with an industria	al adhesive tape, e	e.g. Tesaband 43	331 (www.tesa.de).
					Cover the unders	side of the connect	or moulding and the	e adjacent parts of t	the pcb as well as	s the open sides	s of the connector.
Design	IEC 61076-4-113		type: har-bus64 male, s	pecial version	will prevent heat suffice.	and gases of the	soldering apparatus	s from damaging the	connector. About	140 + 5 mm of	the tape should
No. of contacts	max. 160				Suffice.						
Contact spacing	2,54mm 1000V							e cover with a fast			
Test voltage Contact resistance	max. 20m0hm for rows a	h c	max. 30mOhm for rows d	1 7	from gas and hea		e soldering apparatı	us. As an additional	protection a foil	can be used for	r covering the part
Insulation resistance	min. 10¹²Ohm	, υ, ι	IIIdx. JUIIOIIII TUI TUWS U	J, Z		De Soldered.					
Working current	1A at 70°C (see derating	diagram)			Cross section of	solder nins					
Temperature range	-55°C +125°C			,		over pins					
Termination technology	solder			,	Recommende plat	ed hole diameter: 9	Ø 1± 0,1mm				
~*	,	maximum distance	rows a, b, c	rows d, z							
Clearance & creepage	between 2 rows	clearance	1,2mm	1,2mm	Row z: A= 0,2	21mm² - 0,25mm²	Row a, b, c: A= 0	0,28mm ² - 0,33mm ²	Row d: A= 0,2	29mm² - 0,33mm²	2
	Delweell Z 1'0WS	creepage	1,2mm	1,2mm					. 0.05		
	between 2	clearance	1,2mm	1,0mm	.		0,49 ^{+0,06}		0,6 ^{+0,05}	 =	
	contacts in a row	creepage	1,2mm	1,0mm				_			
Insertion and withdrawal force	max. 160N				0,8_0,03	 - †					
PCB thickness	min. 1,6mm	112	F001' 1		<u> </u>			25		22	
Mating cycles UL file	PL 1 acc. to IEC 61076-4- E102079	-115	500 mating cycles		—— [0,52_0		9,0-9,0		0,5-0,0	
UL THE RoHS – compliant	No (for compliant version	. saa cataloguol		,	— I	0 1	1	0	l	0	
kons – compuant Leadfree	No (for compliant version										
					<u></u>						
Insulator material		:									
		-									
Material	LCP (Liquid Cristal Polym	er)									
Material Color	nature	er)									
Material Color UL classification	nature UL 94-V0	er)									
Material Color	nature	er)									
Material Color UL classification Material group acc. IEC 60664-1	nature UL 94-V0	er)									
Material Color UL classification	nature UL 94-V0	er)									
Material Color UL classification Material group acc. IEC 60664-1 Contact material	nature UL 94-V0 IIIa (175 < CTI < 400)	er)									
Material Color UL classification Material group acc. IEC 60664-1	nature UL 94-V0	er)									
Material Color UL classification Material group acc. IEC 60664-1 Contact material Contact material Plating termination zone	nature UL 94-V0 IIIa (175 < CTI < 400) Copper alloy										
Material Color UL classification Material group acc. IEC 60664-1 Contact material Contact material Plating termination zone Plating contact zone	nature UL 94-V0 Illa (175 < CTI < 400) Copper alloy SnPb over Ni min 1,27µm (50µin) Au over										
Material Color UL classification Material group acc. IEC 60664-1 Contact material Contact material Plating termination zone Plating contact zone	nature UL 94-V0 Illa (175 < CTI < 400) Copper alloy SnPb over Ni min 1,27µm (50µin) Au over										
Material Color UL classification Material group acc. IEC 60664-1 Contact material Contact material Plating termination zone Plating contact zone Derating diagram acc. to IEC 60512-	nature UL 94-V0 Illa (175 < CTI < 400) Copper alloy SnPb over Ni min 1,27µm (50µin) Au over -5 (Current carrying capacity) ited by maximum temperature										
Material Color UL classification Material group acc. IEC 60664-1 Contact material Contact material Plating termination zone Plating contact zone Derating diagram acc. to IEC 60512-	nature UL 94-V0 Illa (175 < CTI < 400) Copper alloy SnPb over Ni min 1,27µm (50µin) Au over -5 (Current carrying capacity) ited by maximum temperature	er 2μm Ni									
Material Color UL classification Material group acc. IEC 60664-1 Contact material Contact material	nature UL 94-V0 Illa (175 < CTI < 400) Copper alloy SnPb over Ni min 1,27µm (50µin) Au over -5 (Current carrying capacity) ited by maximum temperature ts including terminals.	ег 2µm Ni 2,0									
Material Color UL classification Material group acc. IEC 60664-1 Contact material Contact material Plating termination zone Plating contact zone Derating diagram acc. to IEC 60512- The current carrying capacity is lime of materials for inserts and contact in the current capacity curve is valided interrupted current loaded contacts	nature UL 94-V0 Illa (175 < CTI < 400) Copper alloy SnPb over Ni min 1,27µm (50µin) Au over -5 (Current carrying capacity) ited by maximum temperature ts including terminals. for continuous, non se of connectors when	ег 2µm Ni 2,0									
Material Color UL classification Material group acc. IEC 60664-1 Contact material Contact material Plating termination zone Plating contact zone Derating diagram acc. to IEC 60512- The current carrying capacity is limply materials for inserts and contact simultaneous power on all contacts	nature UL 94-V0 Illa (175 < CTI < 400) Copper alloy SnPb over Ni min 1,27µm (50µin) Au over -5 (Current carrying capacity) ited by maximum temperature ts including terminals. for continuous, non se of connectors when	ег 2µm Ni 2,0 [V] peo-				Dimensions in mm	Scale Free size to	ol.	R	Ref.	
Material Color UL classification Material group acc. IEC 60664-1 Contact material Contact material Plating termination zone Plating contact zone Derating diagram acc. to IEC 60512- The current carrying capacity is lime of materials for inserts and contact in the current capacity curve is valided interrupted current loaded contacts	nature UL 94-V0 Illa (175 < CTI < 400) Copper alloy SnPb over Ni min 1,27µm (50µin) Au over -5 (Current carrying capacity) ited by maximum temperature ts including terminals. for continuous, non se of connectors when	ег 2µm Ni 2,0 [V] peo-					Scale Free size to 1:1	ol.	S	Sub. DS 02011200202 / E0	C01482 / 21.04.2011
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Material Color UL classification Material group acc. IEC 60664-1 Contact material Contact material Plating termination zone Plating contact zone Derating diagram acc. to IEC 60512- The current carrying capacity is limple materials for inserts and contact inserts and contact inserts and contact inserts and contact inserts and contacts insultaneous power on all contacts the maximum temperature. Control and test procedures according the contact in the contact in the contact inserts and contacts in the maximum temperature.	nature UL 94-V0 Illa (175 < CTI < 400) Copper alloy SnPb over Ni min 1,27µm (50µin) Au over -5 (Current carrying capacity) ited by maximum temperature ts including terminals. for continuous, non s of connectors when is given, without exceeding ing to DIN IEC 60512-5	ег 2µm Ni 2,0			Ori All rig	ginal Size DIN A3 ghts reserved T	1:1 Instruction In	spected by Sta	S andardisation D FFMANN 2	Sub. DS 02011200202 / E0	State Final Release
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